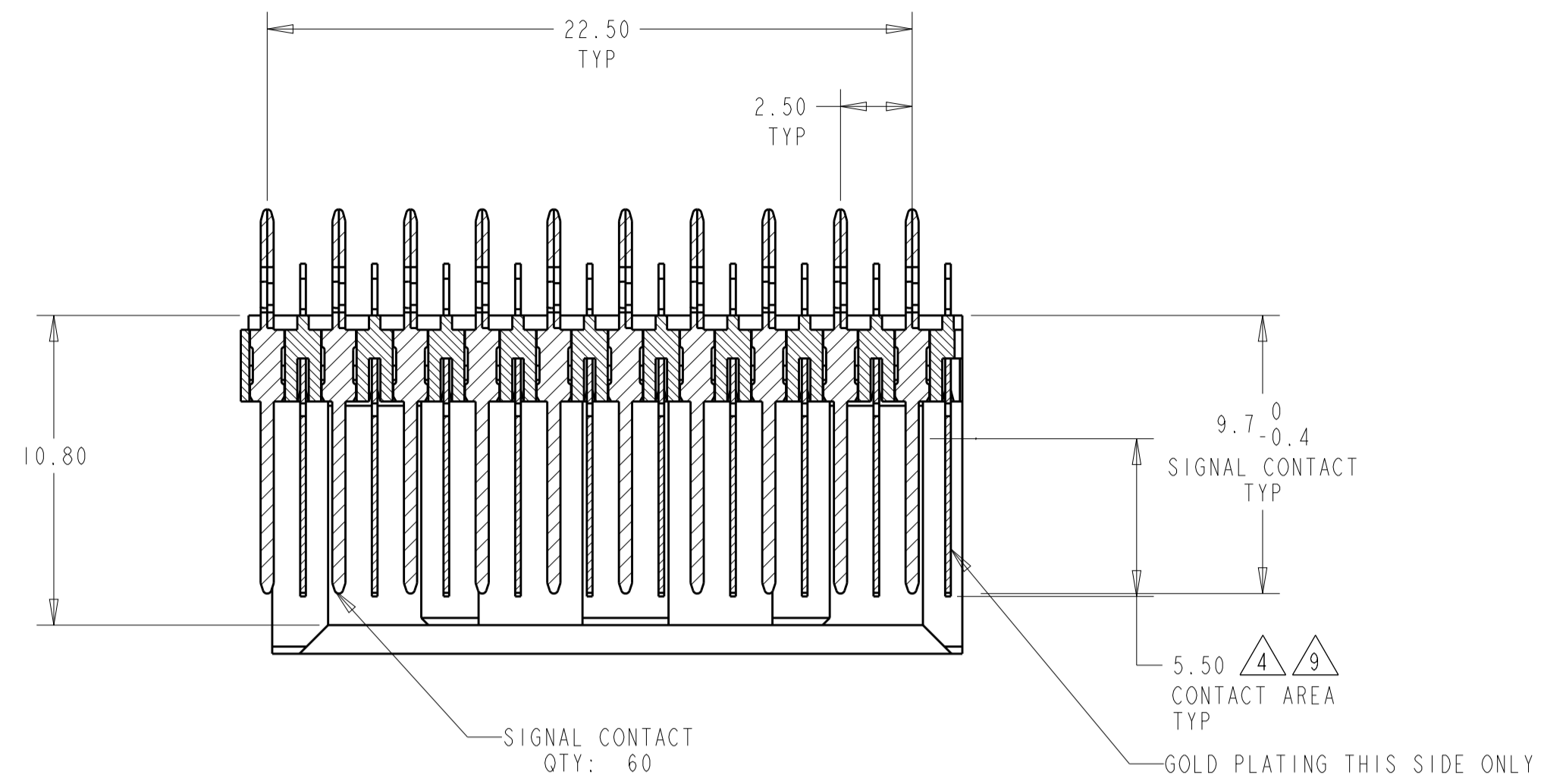
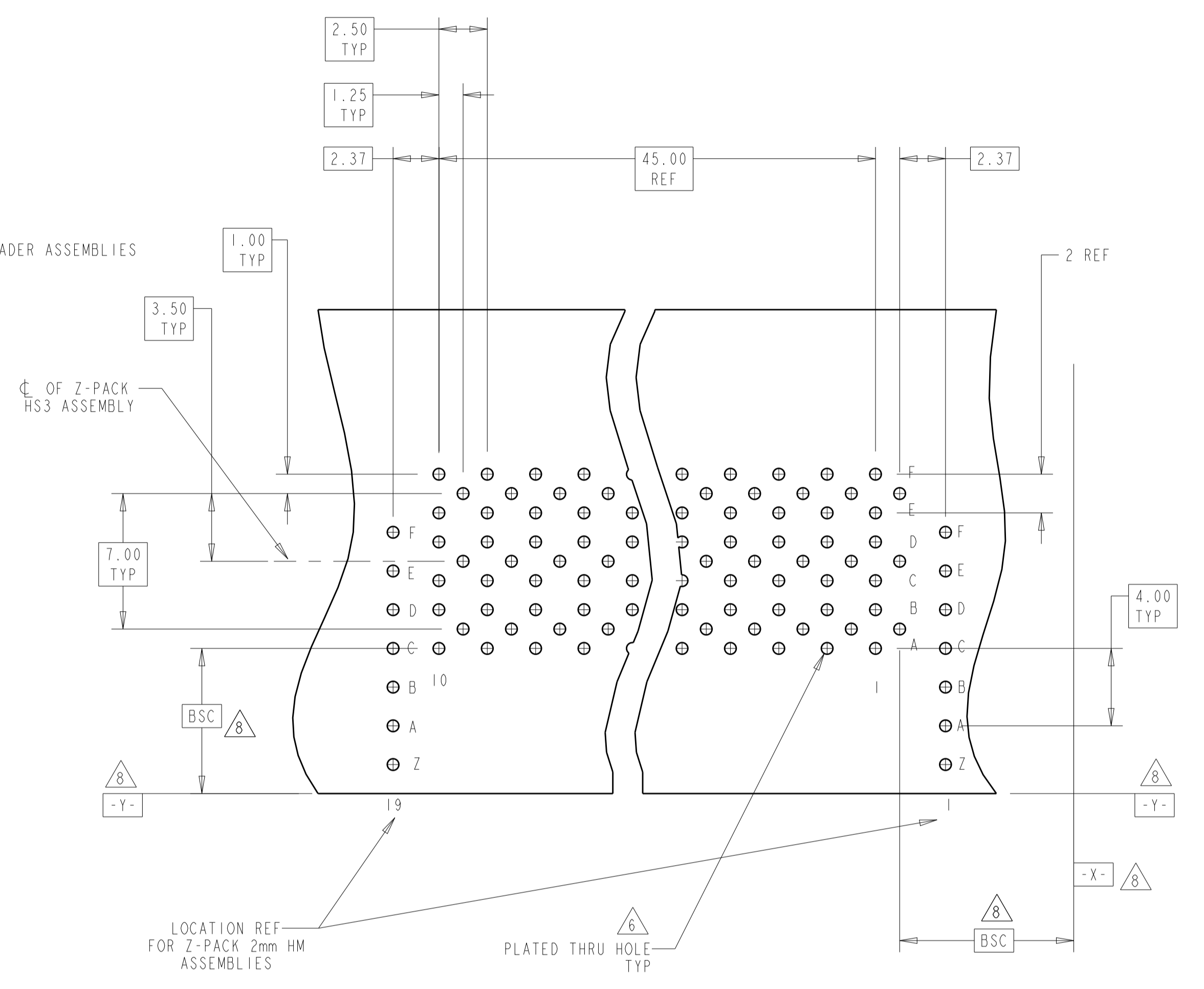
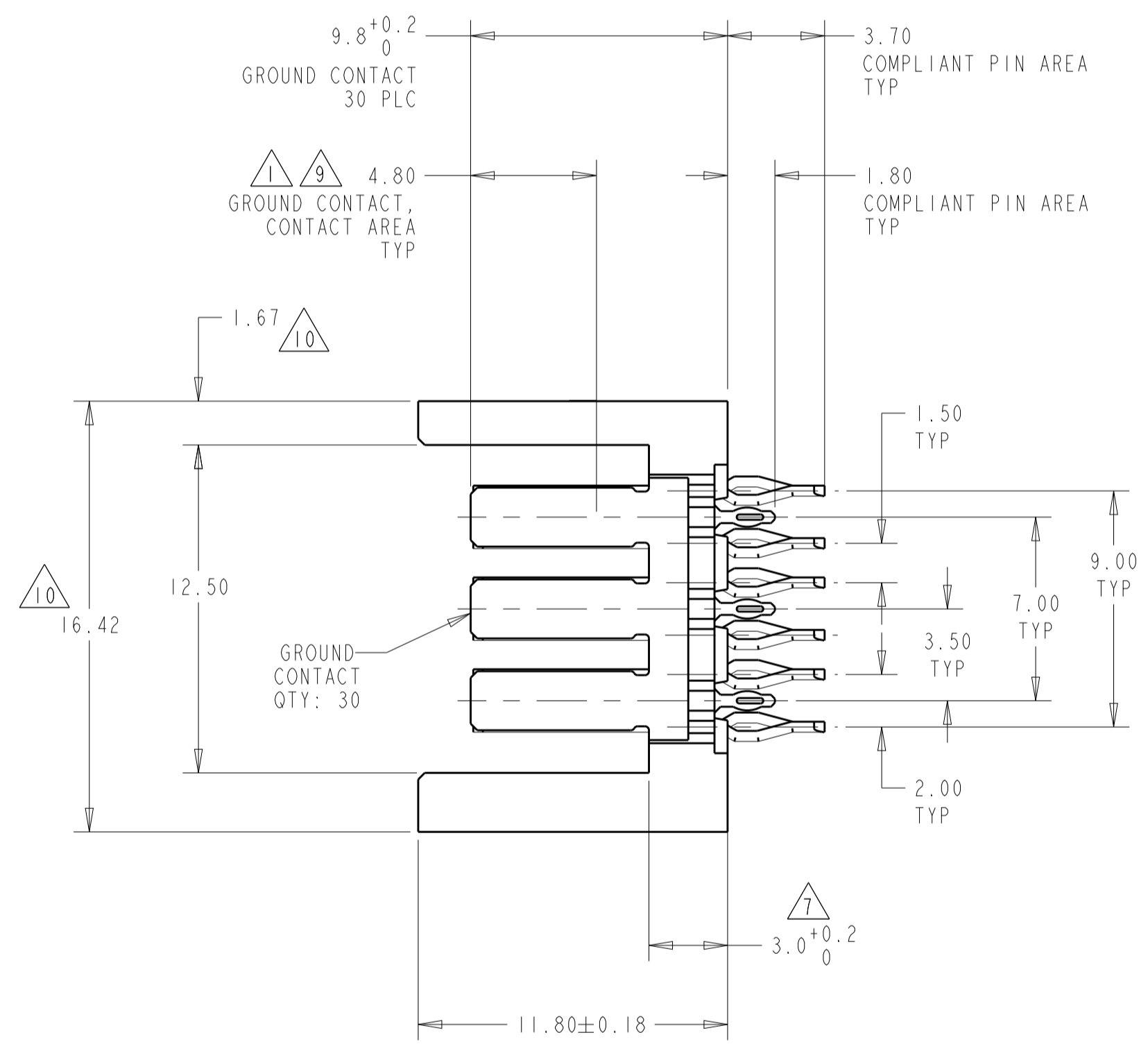
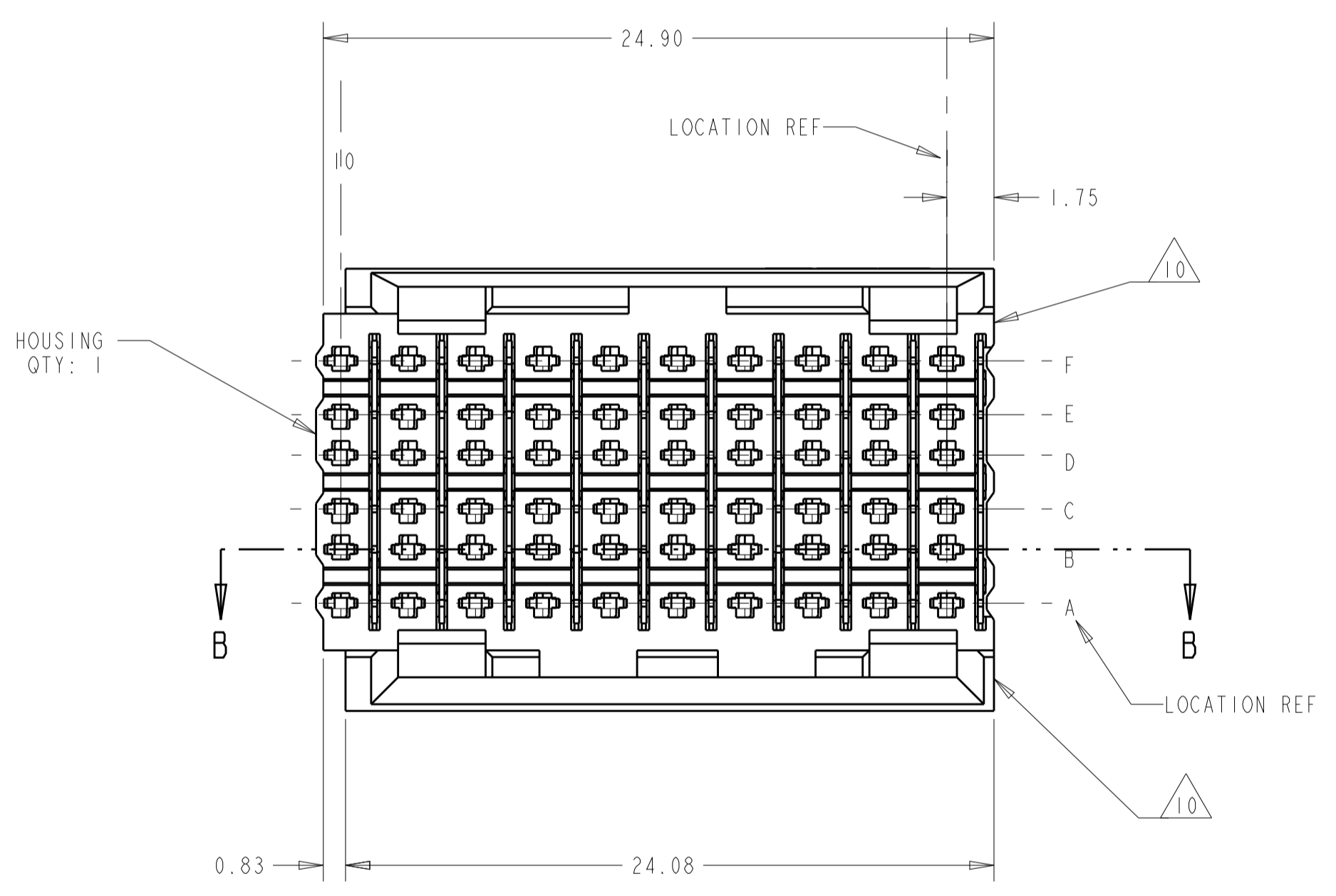


LOC		DIST		REVISIONS			
AD	00	P	LTH	DESCRIPTION	DATE	DWN	APVD
		B		REVISED PER ECO-12-006972	23AUG2012	KH	JE

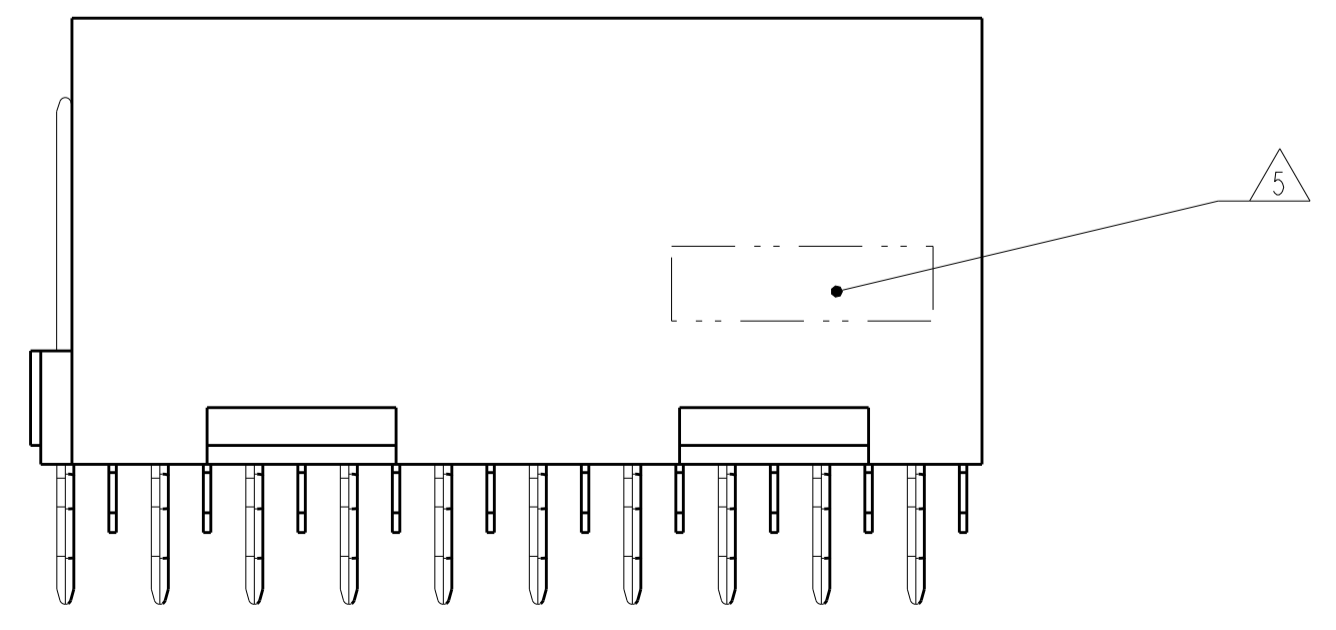


- 1 FINISH: CONTACT MATING AREA MEETS THE PERFORMANCE REQUIREMENTS OF TE CONNECTIVITY PRODUCT SPECIFICATION 108-1957; BASED ON TELCORDIA GR-1217-CORE, APPLICATIONS IN UNCONTROLLED ENVIRONMENTS. COMPLIANT PIN AREA: 0.5µm MIN MATTE TIN OVER BASE PLATING.
- 2 PHOSPHOR BRONZE
- 3 GLASS FILLED POLYESTER
- 4 0.76µm MIN GOLD OVER 1.27µm MIN NICKEL ON CONTACT AREA
 0.76µm MIN TIN OVER 1.27µm MIN NICKEL ON COMPLIANT PIN AREA
- 5 CONNECTOR MARKED WITH PART NUMBER AND DATE CODE
- 6 REFERENCE APPLICATION SPEC 114-13020 FOR RECOMMENDED PLATED THRU HOLE DIAMETER AND PLATING THICKNESS.
- 7 APPLICATION SEATING HEIGHT TO PRINTED CIRCUIT BOARD
- 8 DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
- 9 CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT TECHNICAL REFERENCE: GR-1217-CORE, ISSUE 1, NOVEMBER 1995
- 10 THIS Z-PACK HS3 HEADER IS SPECIFICALLY DESIGNED TO FIT TWO (2) HEADER ASSEMBLIES IN THE P4 POSITION ON A 20mm SLOT PITCH AGAINST Z-PACK 2mm HM 5 ROW HEADER ASSEMBLIES FOR CompactPCI

SECTION B-B



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT FOR P4 CompactPCI APPLICATIONS COMPONENT SIDE OF PRINTED CIRCUIT BOARD



5120826-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. CARBO 08DEC04	TE Connectivity NAME: HEADER ASSEMBLY, 60 POSITION, BACKPLANE CONNECTOR, 6 ROW, Z-PACK HS3 FOR CompactPCI PRODUCT SPEC: 08DEC04 APPLICATION SPEC: 08DEC04 SIZE: A1 CAGE CODE: 00779 DRAWING NO: 5120826 RESTRICTED TO: - SCALE: 5:1 SHEET: 1 OF 1 REV: B
DIMENSIONS: mm		CHK R. PATTERSON 08DEC04	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13 3 PLC ±0.05 4 PLC ± ANGLES ±		APVD R. PATTERSON 08DEC04	
MATERIAL HOUSING: 3 FINISH GROUND CONTACT: 4 CONTACTS: 2 SIGNAL CONTACT: 4		WEIGHT: - CUSTOMER DRAWING	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)